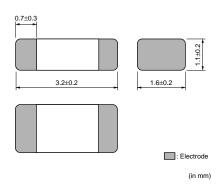
Data Sheet

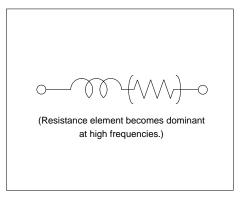
EMIFIL® (Inductor type) Chip Ferrite Bead

BLM31P Series (1206 Size)

■ Dimensions



■ Equivalent Circuit



■ Packaging

Code	Packaging	Minimum Quantity	
L	180mm Embossed Tape	3000	
K	330mm Embossed Tape	10000	
В	Bulk(Bag)	1000	

■ Rated Value (□: packaging code)

Part Number	Impedance (at 100MHz/20°C)	Impedance (at 1GHz/20°C)	Rated Current	DC Resistance(max.)	Operating Temperature Range
BLM31PG330SN1□	33ohm±25%	-	6000mA	0.01ohm	-55°C to +125°C
BLM31PG500SN1□	50ohm(Typ.)	-	3000mA	0.025ohm	-55°C to +125°C
BLM31PG121SN1□	120ohm±25%	-	3000mA	0.025ohm	-55°C to +125°C
BLM31PG391SN1□	390ohm±25%	-	2000mA	0.05ohm	-55°C to +125°C
BLM31PG601SN1□	600ohm±25%	-	1500mA	0.09ohm	-55°C to +125°C

Number of Circuits: 1

Continued on the following page.

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• This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

⚠ Note:

- 1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
- 2. This datasheet has only typical specifications because there is no space for detailed specifications. Therefore, please approve our product specifications or transact the approval sheet for product specifications before ordering.



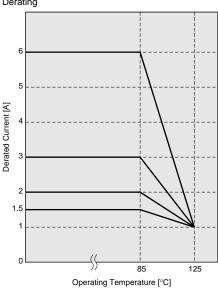
Continued from the preceding page.

■ Derating of Rated Current

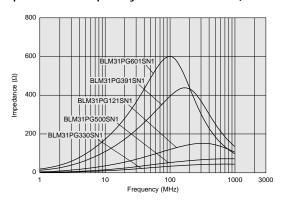
In operating temperature exceeding +85°C, derating of current is necessary for BLM31PG series. Please apply the derating curve shown in chart according to the operating



temperature.

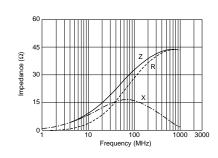


■ Impedance-Frequency Characteristics (Main Items)



■ Impedance-Frequency Characteristics

BLM31PG330SN1



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• This data sheet is applied for CHIP FERRITE BEAD used for General Electronics equipment for your design.

⚠ Note:

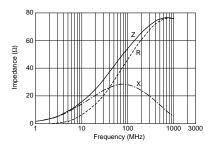
- 1. This datasheet is downloaded from the website of Murata Manufacturing co., ltd. Therefore, it's specifications are subject to change or our products in it may be discontinued without advance notice. Please check with our sales representatives or product engineers before ordering.
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Data Sheet

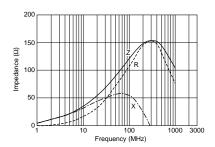
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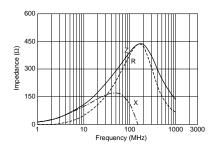
■ Impedance-Frequency Characteristics BLM31PG500SN1



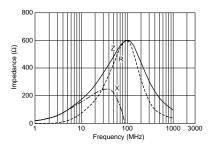
■ Impedance-Frequency Characteristics BLM31PG121SN1



■ Impedance-Frequency Characteristics BLM31PG391SN1



■ Impedance-Frequency Characteristics BLM31PG601SN1



■ ①Caution/Notice

Do not use products beyond the rated current as this may create excessive heat and deteriorate the insulation resistance.

Notice

Solderability of Tin plating termination chip might be deteriorated when low temperature soldering profile where peak solder temperature is below the Tin melting point is used. Please confirm the solderability of Tin plating termination chip before use.

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